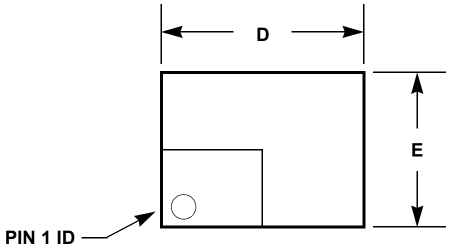
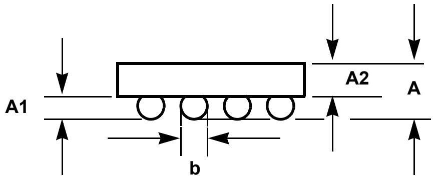
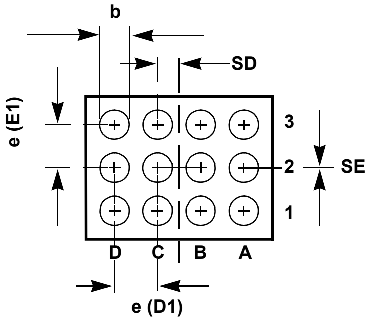
Wafer Level Chip Scale Package (WLCSP 0.4mm Ball Pitch)



TOP VIEW



SIDE VIEW



BOTTOM VIEW

W3x4.12

3x4 ARRAY 12 BALL WAFER LEVEL CHIP SCALE PACKAGE

SYMBOL	MILLIMETERS
A	0.445 Min 0.495 Nom 0.545 Max
A1	0.190 ±0.025
A2	0.305 ±0.025
b	0.270 ±0.030
D	1.695 ±0.020
D1	0.400 BASIC
E	1.295 ±0.020
E1	0.400 BASIC
e	0.400 BASIC
SD	0.200 BASIC
SE	0 BASIC
NUMBER OF BUMPS: 12	

Rev. 0 12/08

NOTES:

1. All Dimensions are in Millimeters.